Amendments to the Claims

1. (Original) A method of preparing a terminal board having a plurality of terminals on which ball electrodes are formed, comprising steps of causing a plurality of terminals to project from surface of a board coated with a resist film, and applying a cutting tool to the surface of the board having the terminals project therefrom to carry out lathe turning for heads of the terminals to make them uniform in height, while having the terminal board held by a rotatable chuck table and rotating the chuck table.

2. (Original) A method of preparing a terminal board according to claim 1, wherein the lathe turning is carried out for heads of the terminals to make them uniform in height with remaining the resist film intact.

3. (Currently Amended) A method of preparing a terminal board according to claim 1 ~~or~~ ~~2~~, wherein the terminal board is an interposer to be interposed between electrodes on a semiconductor chip and electrodes on a mounting board.

4. (Currently Amended) A method of preparing a terminal board according to claim 1 ~~or~~ ~~2~~, wherein copper electrodes are formed as the terminals, and the cutting tool is a single-crystal diamond tool.

5. (Currently Amended) A method of preparing a terminal board according to claim 1 ~~or~~ ~~2~~, wherein the chuck table has a rotating speed of 500 rpm, and the cutting tool has a feed rate of 50 μm per revolution of the chuck table for movement from outer periphery of the chuck table to its center of rotation and makes a cutting depth of 5 to 15 μm.

6. (New) A method of preparing a terminal board according to claim 2, wherein the terminal board is an interposer to be interposed between electrodes on a semiconductor chip and electrodes on a mounting board.

7. (New) A method of preparing a terminal board according to claim 2, wherein copper electrodes are formed as the terminals, and the cutting tool is a single-crystal diamond tool.

8. (New) A method of preparing a terminal board according to claim 2, wherein the chuck table has a rotating speed of 500 rpm, and the cutting tool has a feed rate of 50 μm per revolution of the chuck table for movement from outer periphery of the chuck table to its center of rotation and makes a cutting depth of 5 to 15 μm.